

## 300mA, Ultra-low noise, Small Package Ultra-Fast CMOS LDO Regulator

### General Description

The LP3992 is designed for portable RF and wireless applications with demanding performance and space requirements. The LP3992 performance is optimized for battery-powered systems to deliver ultra low noise and low quiescent current. The LP3992 also works with low-ESR ceramic capacitors, reducing the amount of board space necessary for power applications, critical in hand-held wireless devices. The LP3992 consumes less than 0.1µA in shutdown mode and has fast turn-on time less than 50µs. The other features include ultra low dropout voltage, high output accuracy, current limiting protection, and high ripple rejection ratio. It is available in the 5-lead of SOT23-5 and TSOT23-5 packages.

### Order Information

LP3992	□ □	□ □	□
	F: Pb-Free		
	Package Type		
	B3: SOT23-3		
	B5: SOT23-5		
	J5: TSOT23-5		
	Output Type		
	12:	1.2V	
	15:	1.5V	
	18:	1.8V	
	25:	2.5V	
	28:	2.8V	
	30:	3.0V	
	33:	3.3V	
	36:	3.6V	
	50:	5.0V	

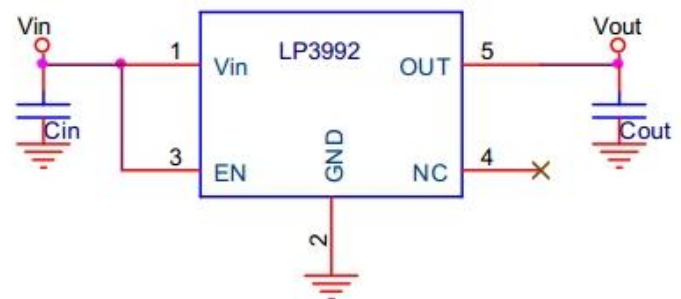
### Features

- ◆ Ultra-Low-Noise for RF Application
- ◆ 2.5V- 5.5V Input Voltage Range
- ◆ Low Dropout : 220mV @ 300mA
- ◆ 1.2V, 1.5V, 1.8V, 2.5V, 2.8V,3.0V,3.3V, 3.6V and 5V Fixed
- ◆ 300mA Output Current
- ◆ High PSRR:-76dB at 1KHz
- ◆ < 1uA Standby Current When Shutdown
- ◆ Available in SOT23-5、 SOT23 and TSOT23-5 Package
- ◆ TTL-Logic-Controlled Shutdown Input
- ◆ Ultra-Fast Response in Line/Load transient
- ◆ Current Limiting and Thermal Shutdown Protection
- ◆ Quick start-up (typically 50uS)

### Applications

- ◇ Portable Media Players/MP3 players
- ◇ Cellular and Smart mobile phone
- ◇ LCD
- ◇ DSC Sensor
- ◇ Wireless Card

### Typical Application Circuit



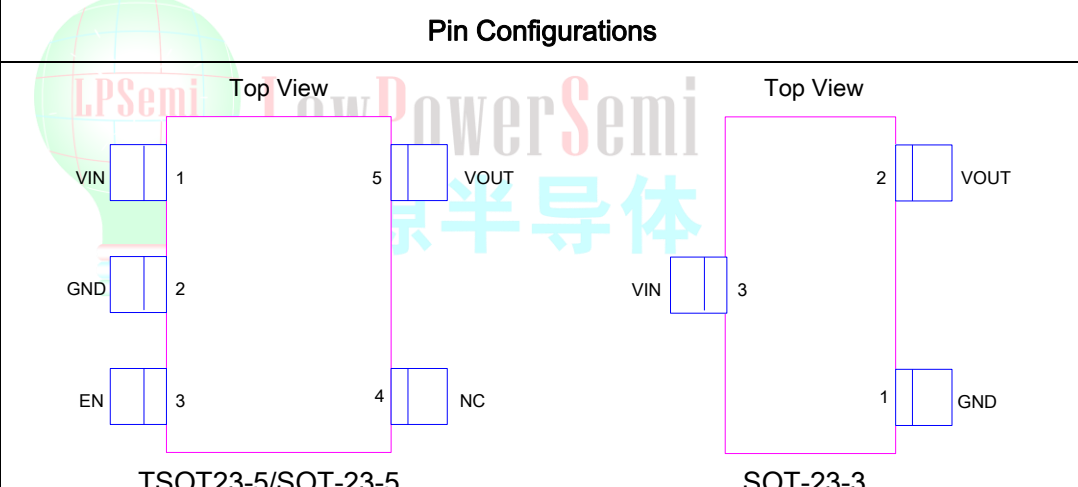
## Marking Information

Device	Marking	Package	Shipping
LP3992-12B5F	LPS	SOT23-3	3K/REEL
	1BYWX	SOT23-5	
		TSOT23-5	
LP3992-15B5F	LPS	SOT23-3	3K/REEL
	1NYWX	SOT23-5	
		TSOT23-5	
LP3992-18B5F	LPS	SOT23-3	3K/REEL
	1CYWX	SOT23-5	
		TSOT23-5	
LP3992-25B5F	LPS	SOT23-3	3K/REEL
	1DYWX	SOT23-5	
		TSOT23-5	

Device	Marking	Package	Shipping
LP3992-28B5F	LPS	SOT23-3	3K/REEL
	1HYWX	SOT23-5	
		TSOT23-5	
LP3992-30B5F	LPS	SOT23-3	3K/REEL
	1GYWX	SOT23-5	
		TSOT23-5	
LP3992-33B5F	LPS	SOT23-3	3K/REEL
	1EYWX	SOT23-5	
		TSOT23-5	

Y: Y is year code. W: W is week code. X: X is series number.

## Functional Pin Description

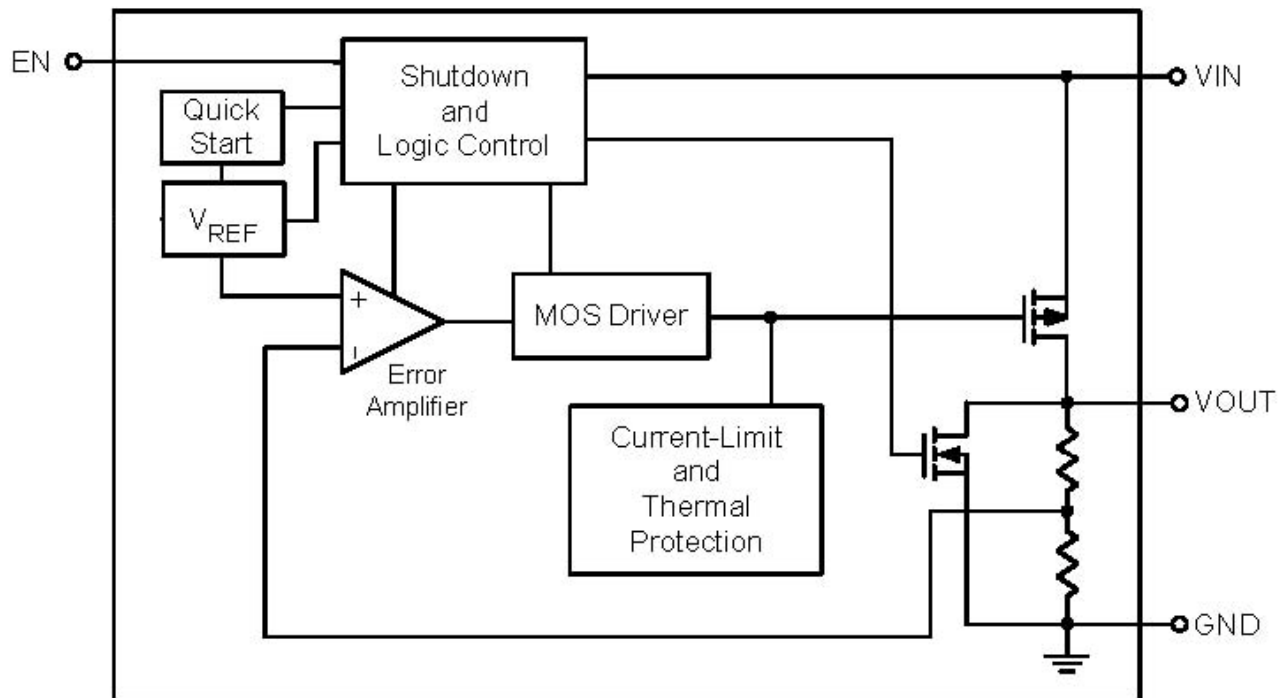
Package Type	Pin Configurations
TSOT23-5 SOT-23-5 SOT-23-3	 <p>Top View</p> <p>Top View</p> <p>TSOT23-5/SOT-23-5</p> <p>SOT-23-3</p>

## Pin Description

Pin		Name	Description
SOT23-5	SOT23-3		
1	3	VIN	Power Input Voltage.
2	1	GND	Ground.
3		EN	Chip Enable (Active High).
4		NC	No Connection.
5	2	VOUT	Output Voltage.



## Function Diagram



## Absolute Maximum Ratings

◇ Supply Input Voltage	-----	6.5V
◇ Other Pin Voltage	-----	-0.3V to VIN+0.3V
<b>Power Dissipation, PD @ TA = 25°C</b>		

◇ T/SOT23-5	-----	500mW
◇ SOT23-3	-----	500mW

### Package Thermal Resistance

◇ Thermal Resistance(SOT23-5/SOT23) (JA)	-----	195°C/W
◇ Thermal Resistance(SOT23-5/SOT23) (JC)	-----	60°C/W
◇ Maximum Junction Temperature	-----	150°C
◇ Maximum Soldering Temperature (at leads, 10 sec)	-----	260°C
◇ Storage Temperature Range	-----	-60°C to 125°C

### ESD Susceptibility

◇ HBM (Human Body Mode)	-----	2kV
◇ MM(Machine-Mode)	-----	200V

### Recommended Operating Conditions

◇ Supply Input Voltage	-----	2.5V to 5.5V
◇ EN Input Voltage	-----	0V to Vin+0.3V
◇ Operation Junction Temperature Range	-----	-40°C to 125°C
◇ Operation Ambient Temperature Range	-----	-40°C to 85°C

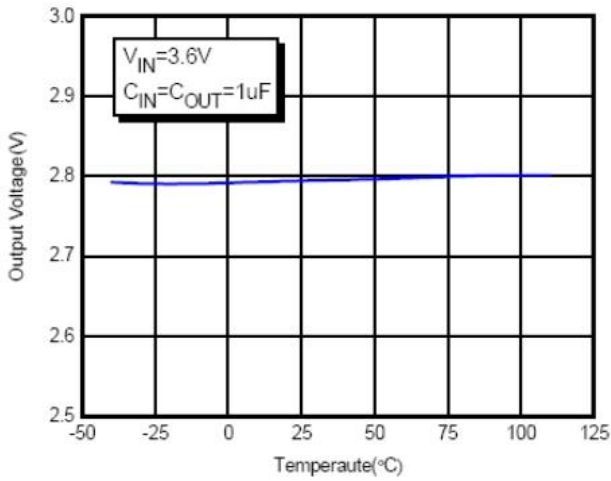
## Electrical Characteristics

(LP3992-33B5F, VIN = VOUT + 1V, CIN = COUT = 1μF, TA = 25° C, unless otherwise specified)

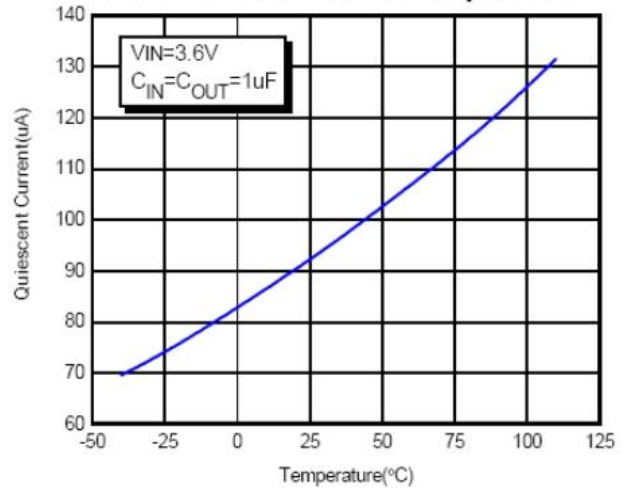
Parameter		Symbol	Test Conditions	Min	Typ.	Max	Units
Output Voltage Accuracy		ΔVOUT	IOUT = 1mA	-3	--	+3	%
Output Voltage		VOUT	IOUT = 1mA		3.33		V
Output Loading Current		ILOAD	VEN=VIN, VIN>2.5V	300			mA
Current Limit		ILIM	RLOAD = 1Ω	420	450		mA
Quiescent Current		IQ	VEN ≥ 1.4V, IOUT = 0mA		75	130	μA
Dropout Voltage		VDROP	IOUT = 200mA, VOUT > 2.8V		130	200	mV
			IOUT = 300mA, VOUT > 2.8V		220	300	
Line Regulation		ΔVLINE	VIN = (VOUT + 1V) to 5.5V, IOUT = 50mA			0.2	%/V
Load Regulation		ΔLOAD	1mA < IOUT < 300mA			2	%/A
Standby Current		ISTBY	VEN = GND, Shutdown		0.01	1	μA
EN Input Bias Current		IIBSD	VEN = 3V		1.5	3.5	μA
EN Threshold	Logic-Low Voltage	VIL	VIN = 3V to 5.5V, Shutdown			0.4	V
	Logic-High Voltage	VIH	VIN = 3V to 5.5V, Start-Up	1.4		VIN+ 0.3	
Output Noise Voltage			10Hz to 100kHz, IOUT = 200mA, COUT = 1μF		300		uVRMS
Power Supply Rejection Rate	f = 1kHz		COUT = 1μF, IOUT = 100mA		-76		dB
	f = 10kHz				-65		
Thermal Shutdown Temperature		TSD			150		°C

## Typical Operating Characteristics

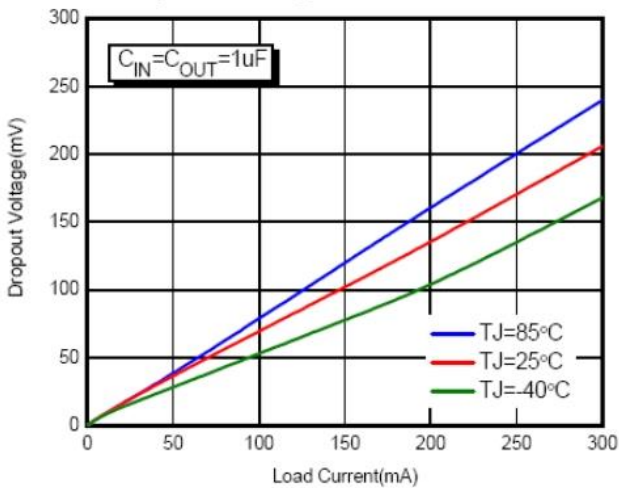
Output Voltage Vs. Temperature



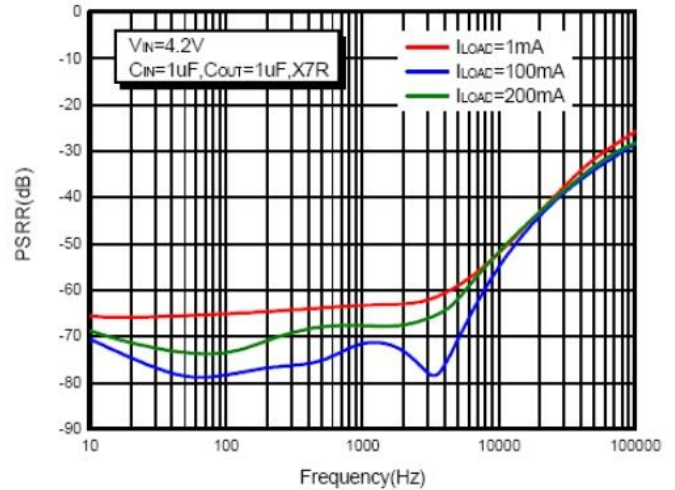
Quiescent Current Vs. Temperature



Dropout Voltage Vs. Load Current



PSRR



## Applications Information

Like any low-dropout regulator, the external capacitors used with the LP3992 must be carefully selected for regulator stability and performance. Using a capacitor whose value is  $> 1\mu\text{F}$  on the LP3992 input and the amount of capacitance can be increased without limit. The input capacitor must be located a distance of not more than 0.5 inch from the input pin of the IC and returned to a clean analog ground. Any good quality ceramic or tantalum can be used for this capacitor. The capacitor with larger value and lower ESR (equivalent series resistance) provides better PSRR and line-transient response. The output capacitor must meet both requirements for minimum amount of capacitance and ESR in all LDOs application. The LP3992 is designed specifically to work with low ESR ceramic output capacitor in space-saving and performance consideration. Using a ceramic capacitor whose value is at least  $1\mu\text{F}$  with ESR is  $> 25\text{m}\Omega$  on the LP3992 output ensures stability. The LP3992 still works well with output capacitor of other types due to the wide stable ESR range. Output capacitor of larger capacitance can reduce noise and improve load transient response, stability, and PSRR. The output capacitor should be located not more than 0.5 inch from the VOUT pin of the LP3992 and returned to a clean analog ground.

### Start-up Function Enable Function

The LP3992 features an LDO regulator enable/disable function. To assure the LDO regulator will switch on, the EN turn on control level must be greater than 1.4 volts. The LDO regulator will go into the shutdown mode when the voltage on the EN pin falls below 0.4 volts. For to protecting the system, the LP3992 have a quick-discharge function. If the enable function is not needed in a specific application, it may be tied to VIN to keep the LDO regulator in a continuously on state.

### Thermal Considerations

Thermal protection limits power dissipation in LP3992. When the operation junction temperature exceeds  $150^\circ\text{C}$ , the OTP circuit starts the thermal shutdown function turn the pass element off. The pass element turns on again after the junction temperature cools by  $25^\circ\text{C}$ . For continue operation, do not exceed absolute maximum operation junction temperature  $125^\circ\text{C}$ .

The power dissipation definition in device is:

$$PD = (VIN - VOUT) \times I_{OUT} + VIN \times I_Q$$

The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of surroundings airflow and temperature difference between junction to ambient.

The maximum power dissipation can be calculated by following formula:

$$PD(\text{MAX}) = (T_J(\text{MAX}) - T_A) / \theta_{JA}$$

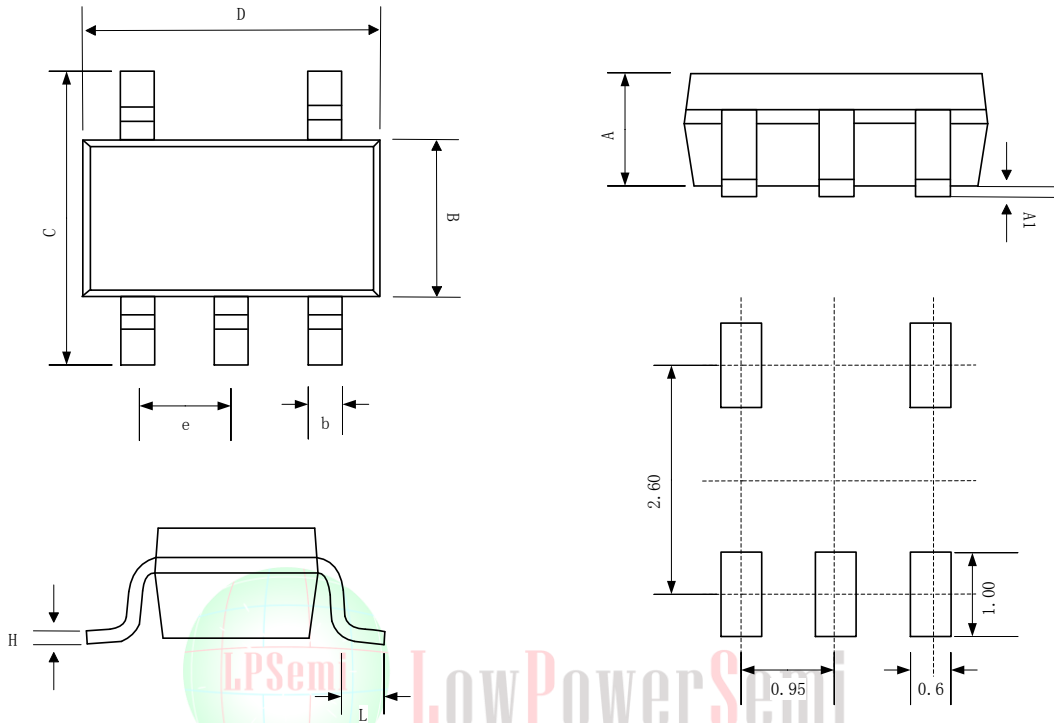
Where  $T_J(\text{MAX})$  is the maximum operation junction temperature  $125^\circ\text{C}$ ,  $T_A$  is the ambient temperature and the  $\theta_{JA}$  is the junction to ambient thermal resistance. For recommended operating conditions specification of LP3992, where  $T_J(\text{MAX})$  is the maximum junction temperature of the die ( $125^\circ\text{C}$ ) and  $T_A$  is the maximum ambient temperature. The junction to ambient thermal resistance ( $\theta_{JA}$  is layout dependent) for SOT23-5 package is  $195^\circ\text{C}/\text{W}$ .

$$PD(\text{MAX}) = (125^\circ\text{C} - 25^\circ\text{C}) / 195 = 500\text{mW}$$

The maximum power dissipation depends on operating ambient temperature for fixed  $T_J(\text{MAX})$  and thermal resistance  $\theta_{JA}$ .

## Packaging Information

### SOT23-5

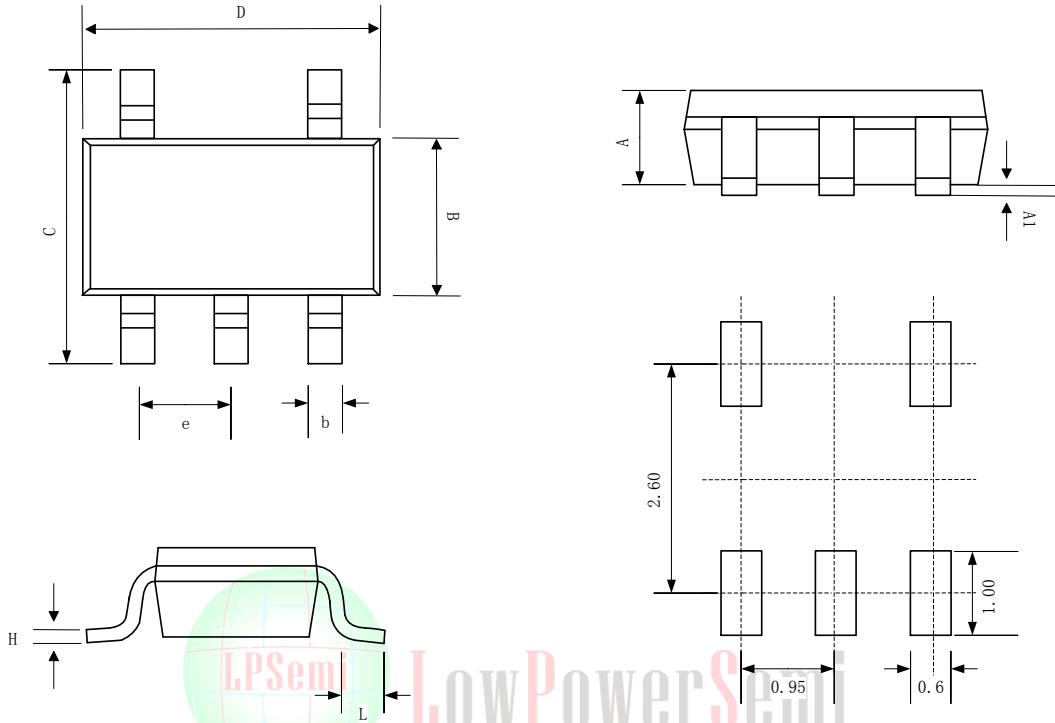


Recommended Land Pattern

SYMBOL	Dimensions In Millimeters		
	MIN	NOM	MAX
A	0.889	1.100	1.295
A1	0.000	0.050	0.152
B	1.397	1.600	1.803
b	0.28	0.35	0.559
C	2.591	2.800	3.000
D	2.692	2.920	3.120
e	0.95BSC		
H	0.080	0.152	0.254
L	0.300	0.450	0.610



TSOT23-5



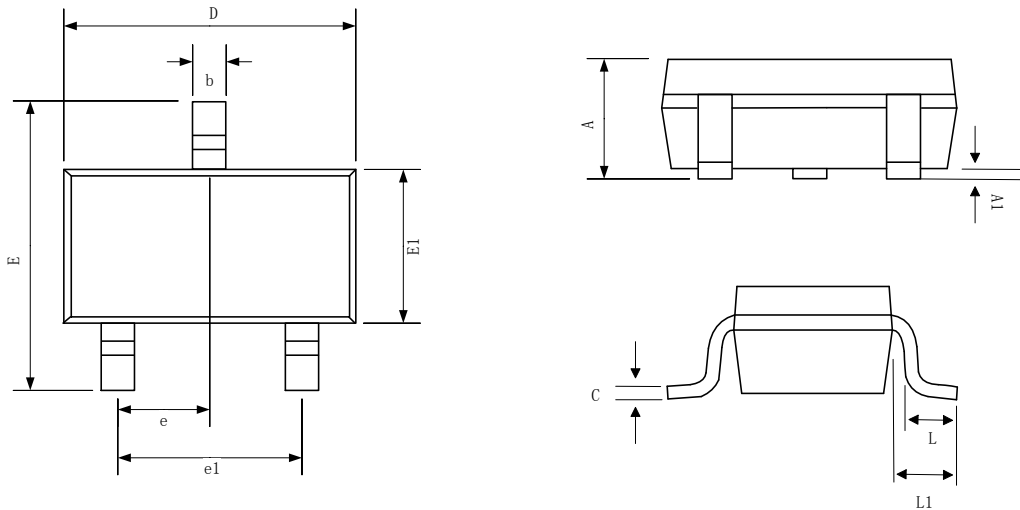
Recommended Land Pattern

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	-	-	1.00
A1	0.00	0.05	0.15
B	1.40	1.60	1.80
b	0.28	0.35	0.56
C	2.59	2.80	3.00
D	2.69	2.92	3.12
e	0.95 BSC		
H	0.08	0.15	0.25
L	0.30	0.45	0.61





SOT23-3



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	1.000	1.150	1.330
A1	0.000	0.050	0.130
b	0.300	0.380	0.450
c	0.110	0.150	0.190
D	2.820	2.920	3.020
E	2.600	2.800	3.000
E1	1.400	1.600	1.800
e	0.950BSC		
e1	1.900BSC		
L	0.300	0.450	0.600
L1	0.600REF		

## Classification of IR Reflow Profile

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat/Soak</b>		
Temperature Min( $T_{SMIN}$ )	100°C	150°C
Temperature Max( $T_{SMAX}$ )	150°C	200°C
Time( $T_s$ ) from ( $T_{SMIN}$ to $T_{SMAX}$ )	60~120 seconds	60~120 seconds
Ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max	3°C/second max
Liquidous temperature( $T_L$ )	183°C	217°C
Time( $t_L$ ) maintained above $T_L$	60~150 seconds	60~150 seconds
Peak package body temperature ( $T_P$ )	For users $T_P$ must not exceed the Classification temp in Table 1. For suppliers $T_P$ must equal or exceed the Classification temp in Table 1.	For users $T_P$ must not exceed the Classification temp in Table 2. For suppliers $T_P$ must equal or exceed the Classification temp in Table 2.
Time( $t_p$ )* within 5°C of the specified classification temperature( $T_c$ ), see Figure 1	20* seconds	30* seconds
Ramp-down rate ( $T_P$ to $T_L$ )	6°C/second max	6°C/second max
Time 25°C to peak temperature	6 minutes max	8 minutes max
* Tolerance for peak profile temperature ( $T_P$ ) is defined as a supplier minimum and a user maximum.		

Table 1 Sn-Pb Eutectic Process - Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 Pb-Free Process - Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350~2000	Volume mm <sup>3</sup> ≥350
<1.6mm	260°C	260°C	260°C
1.6mm~2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

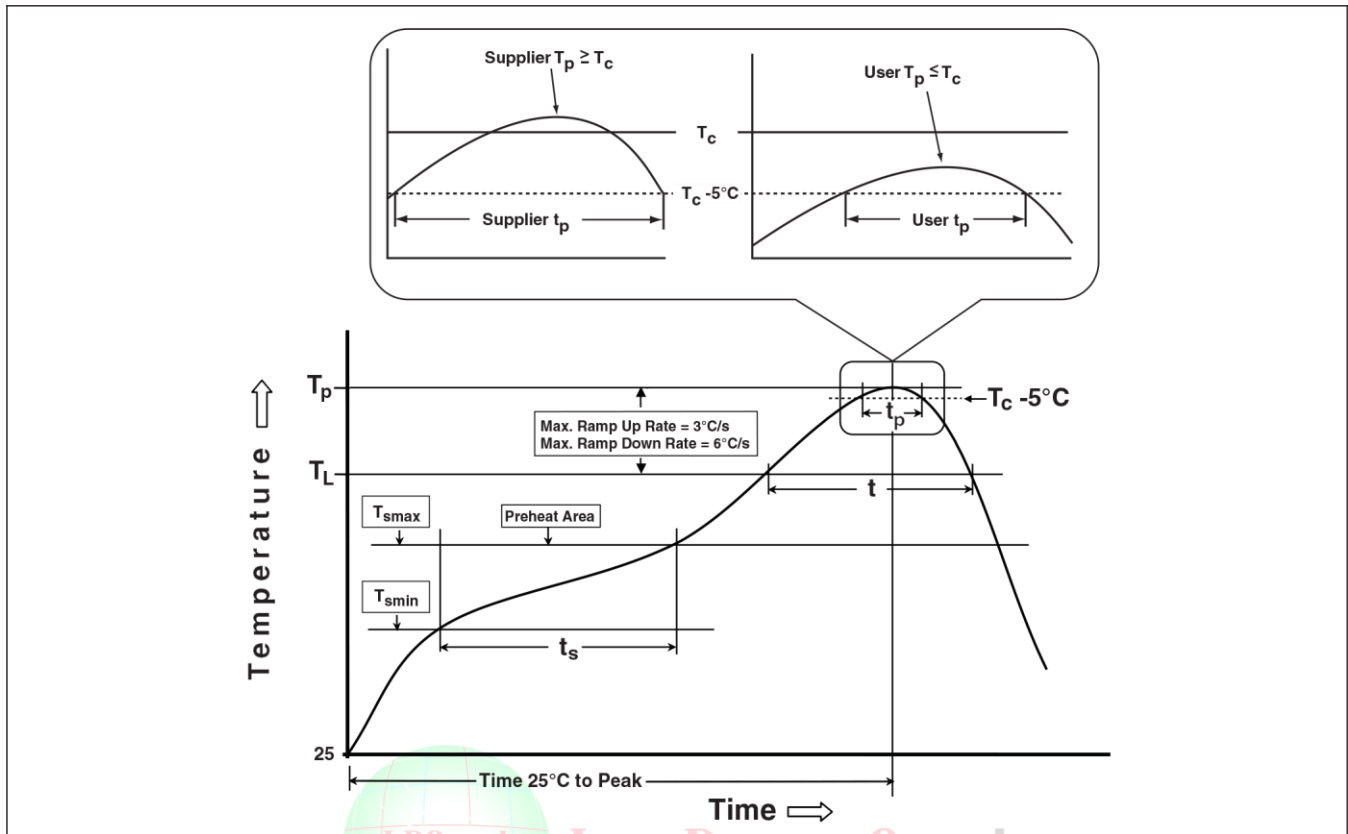


Figure 1 Classification Profile (Not to scale)

Products shipped conform to “Rohs” standards;

Moisture Sensitivity Level: MSL3 (CONDITION:  $\leq 30\text{ }^{\circ}\text{C}/60\%\text{RH}$ 、Time control:168 hours) ;